

June 17, 2022

Name of Company KAGA ELECTRONICS CO., LTD.  
Representative Ryoichi Kado,  
Representative Director, President & COO  
(Stock Code: 8154 Tokyo Stock Exchange, Prime Market)  
Contact Eiji Kawamura,  
Director, Managing Executive Officer  
Head of Administration Headquarters  
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## Notice of Issuance of Unsecured Corporate Bonds

Kaga Electronics Co., Ltd. (hereinafter, "the Company") hereby announces that it has determined the terms for the issuance of the 1st and 2nd round of unsecured corporate bonds (subject to a designated inter-bond pari passu clause; hereinafter the "Unsecured Corporate Bonds"). An overview of the Unsecured Corporate Bonds is presented below.

The issuance of the Unsecured Corporate Bonds is aimed at diversifying the Company's methods of financing. This will be the first time the Company has issued such unsecured corporate bonds.

1. Name of the unsecured corporate bonds	Kaga Electronics Co., Ltd. 1st Round Unsecured Corporate Bonds (Subject to a designated inter-bond pari passu clause)	Kaga Electronics Co., Ltd. 2nd Round Unsecured Corporate Bonds (Subject to a designated inter-bond pari passu clause)
2. Maturity	3 years	5 years
3. Total amount of issue	5,000 million yen	5,000 million yen
4. Face value each unsecured corporate bond	100 million yen	
5. Interest rate	0.400% per annum	0.500% per annum
6. Issue price	100 yen per 100 yen of face value	
7. Redemption method	Redemption in full at maturity Redemption deadline: Monday, June 23, 2025	Redemption in full at maturity Redemption deadline: Wednesday, June 23, 2027
8. Payment dates	June 23 and December 23 each year (first payment date: Friday, December 23, 2022)	
9. Method of offering	Public offering	
10. Offering date	Friday, June 17, 2022	
11. Pay-in date	Thursday, June 23, 2022	
12. Collateral and guarantees	These unsecured corporate bonds are not secured by any collateral or guarantees, and no assets have been retained specifically to secure them.	
13. Financial clauses	The unsecured corporate bonds carry a negative pledge clause (designated inter-bond pari passu clause).	
14. Lead managing underwriters	Nomura Securities Co., Ltd. and Mitsubishi UFJ Morgan Stanley Securities Co., Ltd.	
15. Financial agent	MUFG Bank, Ltd.	
16. Rating	A- (JCR)	